																				
						<u> </u>		RE	visi	ons										
LTR					DF	ESCRI	PTIO	N					D/	ATE ((YR-MO-	-DA)	E	APPRO	VED	
查询	5962-	-9084	201 N	IGX"	供应	商														1
						•														
																				1
																				ł
													•							
									•											
			Γ				Γ	T	Ţ			[]		Γ—						\square
REV																		$\vdash \vdash$	\prod	
SHEET								<u> </u>		.,										
REV																			\square	
SHEET REV STATE	 Пе	<u> </u>	<u></u>	RE		<u> </u>	<u></u>	 	 	,										
OF SHEET:					EET		1	2	3	4	5	6	7	8	9	10	11	12		
DMTC N/A				1	ARED E				1	_										<u></u>
PMIC N/A				1	uk	<u>. (.</u>	01	fice	<u> </u>	D	EFENS				S SU OHIO			ΓER		
STAND MII.	ARD])	CHEC	KED A	r - (Off E B	-) -	-								····			
	AWIN				للام	•	<u> </u>	Ret	re	MIG	CROC	IRC	JIT,	, LI	NEAF	R, P	REC1	ISIO	N, J	COM
THIS DRAWIN				APPR	ROVED E	3Y			R		-	OPI			AL A	MPL	IFIE	≅R,		
FOR USE BY A AND AGEN DEPARTMEN	CIES C	OF THE		DRAW		PPROVAL				Pio	NOT T	Thi	- 31	.ш.с	<u></u>					
VEFARING	li Ur u	JEFENS	E	<u> </u>	92-	- 10-2	29			SIZ	E		E CO			 59	- 962-	-9084	42	
AMSC N/A	١.			REVI	ISION I	LEVEL				A			5726	8	<u></u>					
										SH	EET		1		OF		12			

DESC FORM 193

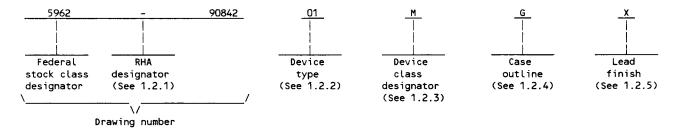
JUL 91

<u>DISTRIBUTION STATEMENT A</u>. Approved for public release; distribution is unlimited.

5962-E356

1. SCOPE

- - 1.2 PIN. The PIN shall be as shown in the following example:



- 1.2.1 <u>Radiation hardness assurance (RHA) designator</u>. Device classes M, B, and S RHA marked devices shall meet the MIL-M-38510 specified RHA levels and shall be marked with the appropriate RHA designator. Device classes Q and V RHA marked devices shall meet the MIL-I-38535 specified RHA levels and shall be marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.
 - 1.2.2 <u>Device type(s)</u>. The device type(s) shall identify the circuit function as follows:

Device type	<u>Generic number</u>	<u>Circuit function</u>
01	LT1012	Precision, low drift, operational amplifier
02	LT1012A	Precision, low drift, operational amplifier

1.2.3 <u>Device class designator</u>. The device class designator shall be a single letter identifying the product assurance level as follows:

<u>Device class</u>	Device requirements documentation
М	Vendor self-certification to the requirements for non-JAN class B microcircuits in accordance with 1.2.1 of MIL-STD-883
B or S	Certification and qualification to MIL-M-38510
Q or V	Certification and qualification to MIL-I-38535

1.2.4 Case outline(s). The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

Outline letter	<u>Descriptive</u> designator	<u>Terminals</u>	<u>Package style</u>
G	MACY1-X8	8	Can
P	GDIP1-T8 or CDIP2-T8	8	Dual-in-line

1.2.5 <u>Lead finish</u>. The lead finish shall be as specified in MIL-M-38510 for classes M, B, and S or MIL-I-38535 for classes Q and V. Finish letter "X" shall not be marked on the microcircuit or its packaging. The "X" designation is for use in specifications when lead finishes A, B, and C are considered acceptable and interchangeable without preference.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER	SIZE A		5962-90842
DAYTON, OHIO 45444		REVISION LEVEL	SHEET 2

1.3 Absolute maximum ratings. 1/								
#20 V Differential input current 2 中面 Input voltage (V _{IN}) #20 V Power dissipation (P _D) #24 mW Output short circuit duration Indefinite Storage temperature range #300°C Lead temperature (soldering, 10 seconds) #300°C Thermal resistance, junction-to-case (θ _{JC}) See MIL-STD-1835 Thermal resistance, junction-to-ambient (θ _{JA}): Case G #150°C/W Case P #150°C/W								
1.4 Recommended operating conditions.								
Supply voltage (V _S)	±15 V 55°C to +125	°c						
2. APPLICABLE DOCUMENTS								
2.1 Government specifications, standards, bulletin, and specifications, standards, bulletin, and handbook of the is of Specifications and Standards specified in the solicitat herein.	ssue listed in th	at issue of the Departmen	t of Defense Index					
SPECIFICATIONS								
MILITARY	MILITARY							
MIL-M-38510 - Microcircuits, General Specification for. MIL-I-38535 - Integrated Circuits, Manufacturing, General Specification for.								
STANDARDS								
MILITARY	MILITARY							
MIL-STD-480 - Configuration Control-Engineering Changes, Deviations and Waivers. MIL-STD-883 - Test Methods and Procedures for Microelectronics. MIL-STD-1835 - Microcircuit Case Outlines.								
BULLETIN								
MILITARY								
MIL-BUL-103 - List of Standardized Military Drawi	ngs (SMD's).							
HANDBOOK								
MILITARY								
MIL-HDBK-780 - Standardized Military Drawings.								
(Copies of the specifications, standards, bulletin, and handbook required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)								
2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.								
 Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability. Differential input voltages greater than 1 V will cause excessive current to flow through the input protection diodes unless limiting resistance is used. 								
STANDARDIZED MILITARY DRAWING	SIZE A		5962-90842					
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET					

3. REQUIREMENTS

3.4. Litem requirements of the mindividual item requirements for device class M shall be in accordance with 1.2.1 of MIL_STD-883 in conjunction with compliant non-JAN devices" and as specified herein. The individual item requirements for device classes B and S shall be in accordance with MIL-M-38510 and as specified herein. For device classes B and S, a full electrical characterization table for each device type shall be included in this SMD. The individual item requirements for device classes Q and V shall be in accordance with MIL-I-38535, the device manufacturer's Quality Management (QM) plan, and as specified herein.

- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 for device classes M, B, and S and MIL-I-38535 for device classes Q and V and herein.
 - 3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein.
 - 3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 1.
- 3.3 <u>Electrical performance characteristics and postirradiation parameter limits</u>. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.
- 3.5 <u>Marking</u>. The part shall be marked with the PIN listed in 1.2 herein. Marking for device class M shall be in accordance with MIL-STD-883 (see 3.1 herein). In addition, the manufacturer's PIN may also be marked as listed in MIL-BUL-103. Marking for device classes B and S shall be in accordance with MIL-M-38510. Marking for device classes Q and V shall be in accordance with MIL-I-38535.
- 3.5.1 <u>Certification/compliance mark</u>. The compliance mark for device class M shall be a "C" as required in MIL-STD-883 (see 3.1 herein). The certification mark for device classes B and S shall be a "J" or "JAN" as required in MIL-M-38510. The certification mark for device classes Q and V shall be a "QML" as required in MIL-I-38535.
- 3.6 <u>Certificate of compliance</u>. For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.7.3 herein). For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.7.2 herein). The certificate of compliance submitted to DESC-EC prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device class M the requirements of MIL-STD-883 (see 3.1 herein), or for device classes Q and V, the requirements of MIL-I-38535 and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required for device class M in MIL-STD-883 (see 3.1 herein) or device classes B and S in MIL-M-38510 or for device classes Q and V in MIL-I-38535 shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change for device class M</u>. For device class M, notification to DESC-EC of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change as defined in MIL-STD-480.
- 3.9 <u>Verification and review for device class M</u>. For device class M, DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
- 3.10 <u>Microcircuit group assignment for device classes M, B, and S</u>. Device classes M, B, and S devices covered by this drawing shall be in microcircuit group number 49 (see MIL-M-38510, appendix E).
- 3.11 <u>Serialization for device class S</u>. All device class S devices shall be serialized in accordance with MIL-M-38510.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER	SIZE A		5962-90842
DAYTON, OHIO 45444		REVISION LEVEL	SHEET 4

查询"5962-908420	1MGX"(Conditions		Group A	Device	 Limit	:s <u>1</u> /	 Unit
		$-55^{\circ}C \le T_A \le +125^{\circ}C$ $V_S = \pm 15 \text{ V, } V_{CM} = 0 \text{ V}$ unless otherwise specifies	ied	subgroups	s type	 Min	Max	
Input offset	v _{os}			4	 01	35	35	μν
voltage				2, 3		 -180	180	.
				4	02	-25	25	
				2, 3	<u> </u>	-60	60	
		<u>2</u> /	1 !	1	_ 01	 <u>-90</u>	90	
			ļ	2, 3	<u> </u>	 -250	250	.] .]
			1	1	_ 02	 <u>-90</u>	90	
				2, 3	ļ	 -180	180	
Input offset	Ios			1	All		100	pA
current				2, 3	-		250	
		2/		1	-		150	
				2, 3			350	
Input bias current	I _B			1	_ ALL	-100	100	pA
				2, 3	_	-600	600	.
		<u>2</u> /		1	_ _	-150	150	_
	-			2, 3	<u> </u>	-800	800	<u> </u>
Common-mode	CMRR	V _{CM} = ±13.5 V		1	_ 01	114	<u> </u>	dB
rejection ratio				2, 3	ļ	108		_
	ļ			1	 _ 02	114	<u> </u>	- !
				2, 3	<u> </u>	110	1	<u> </u>
Power supply rejection ratio	 PSRR 	V _S = ±1.2 V to ±20 V		 1	ALL	114		dB
-		V _S = ±1.5 V to ±20 V		2, 3	01	108		
		<u> </u>			02	110		
Input voltage range	+V _{IN}	 <u>3</u> / _		1, 2, 3	ALL	+13.5		 v _
	-VIN			 		 	-13.5	<u> </u>
See footnotes at end o	of table.						_	
MILI	TANDARD	RAWING	SIZE				596	52-9084
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444					VISION		-	ET

查询。5962-908420)1 <mark>MG&"(1</mark>	<mark>井应商</mark> Conditions -55°C ≤ T _A ≤ +125°C	$ \overline{Y}$ Conditions Group A $ \overline{Y} $ Subgroups Subgroups		Limits <u>1</u> /		Unit
		$-55^{\circ}C \le T_A \le +125^{\circ}C$ $V_S = \pm 15 V, V_{CM} = 0 V$ unless otherwise specified			Min	Max	1
Total supply current	I _{SY}		11	01		600	μA
	ļ		2, 3	<u> </u>	<u> </u>	800	
			11	02		500	
			2, 3	1	<u> </u>	650	-
Average temperature coefficient of	TCVos	<u>3</u> /	5, 6	01		1.5	 μν/°c
Vos				02	! -	0.6	
Average temperature coefficient of ^I OS	TCIOS	3/	5, 6	All		2.5	pA/°C
Average temperature coefficient ^I B	TCIB	3/	5, 6	ALL		6.0	pA/°C
Input noise voltage density	e _N	f _O = 10 Hz, T _A = +25°C 4/	4	ALL		30	nV/√Hz
	 	f _O = 1 kHz, T _A = +25°C <u>5</u> /		 	 	22	
Large signal	A _{VOL}	V _{OUT} = ±12 V, R _L ≥ 10 kΩ	4	_ 01	300		V/mV
voltage gain		R _L ≥ 10 kΩ 	5, 6		150		
			4	 02	300		1
			5,6	<u> </u>	200		i
		$V_{OUT} = \pm 10 \text{ V},$ $R_{L} \ge 2 \text{ k}\Omega$	4	_ 01	200		
		R _L ≥ 2 kΩ	5, 6	, 	 100		_ _
	1		4	02	300		- -
			5,6		200		

SIZE

A

REVISION LEVEL

5962-90842

6

SHEET

DESC FORM 193A JUL 91

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER

DAYTON, OHIO 45444

查询。5962-9084	1201 MGX"(f	-55°C ≤ T _A ≤ +125°C		Device type	Limits <u>1</u> /		Unit
		V _S = ±15 V, V _{CM} = 0 V unless otherwise specified		<u> </u>	Min	Max	ļ
Output voltage swing	+V _{OUT}	$ R_L = 10 \text{ k}\Omega$	4, 5, 6	ALL	+13 	 	 v _
	-V _{OUT}		 			-13	
Slew rate	+SR	Rising edge, $C_L = 20 \text{ pF}$, $R_L = 2 \text{ k}\Omega$, $V_{OUT} = -5.0 \text{ V}$ to +5.0 V, measured from -2.5 V to +2.5 V, $T_A = +25^{\circ}\text{C}$	7	ALL	0.1		V/µs
	-SR	Falling edge, C _L = 20 pF, R _L = 2 kΩ, V _{OUT} = +5.0 V to -5.0 V, measured from +2.5 V to -2.5 V, T _A = +25°C	7		0.1		

 $[\]underline{1}$ / The algebraic convention, whereby the most negative value is a minimum and the most positive is a maximum, is used in this table. Negative current shall be defined as conventional current flowout of a device terminal.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER	SIZE A		5962-90842
DAYTON, OHIO 45444		REVISION LEVEL	SHEET 7

^{2/} Unless otherwise specified, ±1.2 V ≤ V_S ≤ ±20 V applies for subgroup 1, ±1.5 V ≤ V_S ≤ ±20 V applies for subgroups 2 and 3, -13.5 V ≤ V_{CM} ≤ +13.5 V at V_S = ±15 V applies for subgroups 1, 2, and 3.

3/ If not tested, shall be guaranteed to the limits specified in table I herein.

4/ Noise voltage density at 10 Hz is sample tested on every lot.

5/ This parameter is tested on a sample basis only.

查询"5962-9084201MGX"供应商

Device types	01 and 02
Case outlines	G and P
Terminal number	Terminal symbol
1 2 3 4 5 6 7 8	VOSTRIM INPUT- INPUT+ VS- OVERCOMP OUTPUT VS+ VOSTRIM

FIGURE 1. <u>Terminal connections</u>.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-90842
		REVISION LEVEL	SHEET 8

TABLE II. Electrical test requirements.

查询"5962-90842014MGX#供应	(in accord	Subgroups (in accordance with MIL-STD-883, method 5005, table I)			Subgroups (in accordance with MIL-I-38535, table III)	
	Device class M	Device class	Device class	Device class Q	Device class	
Interim electrical parameters (see 4.2)						
Final electrical parameters (see 4.2)	1,2,3, <u>1</u> / 4,5,6,7	 1,2,3, <u>1</u> / 4,5,6,7	1,2,3, <u>1</u> / 4,5,6,7	1,2,3, <u>1</u> / 4,5,6,7	1,2,3, <u>1</u> / 4,5,6,7	
Group A test requirements (see 4.4)	1,2,3,4,	1,2,3,4, 5,6,7	1,2,3,4, 5,6,7	1,2,3,4, 5,6,7	1,2,3,4, 5,6,7	
Group B end-point electr parameters (see 4.4)	rical		1,2,3,4, 5,6,7			
Group C end-point electr parameters (see 4.4)	rical 1	1 1	 	1	 1,2,3,4, 5,6,7	
Group D end-point electr parameters (see 4.4)	rical 1	1	1	1	1	
Group E end-point electr parameters (see 4.4)	rical		 			

^{1/} PDA applies to subgroup 1.

4. QUALITY ASSURANCE PROVISIONS

- 4.1 <u>Sampling and inspection</u>. For device class M, sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein). For device classes B and S, sampling and inspection procedures shall be in accordance with MIL-M-38510 and method 5005 of MIL-STD-883, except as modified herein. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-I-38535 and the device manufacturer's QM plan.
- 4.2 <u>Screening</u>. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. For device classes B and S, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to qualification and quality conformance inspection. For device classes Q and V, screening shall be in accordance with MIL-I-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection.
 - 4.2.1 Additional criteria for device classes M, B, and S.
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition C. For device class M, the test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. For device classes B and S, the test circuit shall be submitted to the qualifying activity. For device classes M, B, and S, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015.
 - (2) $T_{\Delta} = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-90842
		REVISION LEVEL	SHEET 9

4.2.2 Additional criteria for device classes Q and V.

- 查询下的 proving rest purple condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's of plan in accordance with MIL-I-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-I-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015.
- b. Interim and final electrical test parameters shall be as specified in table II herein.
- c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in appendix B of MIL-I-38535.
- 4.3 Qualification inspection.
- 4.3.1 <u>Qualification inspection for device classes B and S.</u> Qualification inspection for device classes B and S shall be in accordance with MIL-M-38510. Inspections to be performed shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.5).
- 4.3.2 <u>Qualification inspection for device classes Q and V</u>. Qualification inspection for device classes Q and V shall be in accordance with MIL-I-38535. Inspections to be performed shall be those specified in MIL-I-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.5).
- 4.4 <u>Conformance inspection</u>. Quality conformance inspection for device class M shall be in accordance with MIL-STD-883 (see 3.1 herein) and as specified herein. Quality conformance inspection for device classes B and S shall be in accordance with MIL-M-38510 and as specified herein. Inspections to be performed for device classes M, B, and S shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.5). Technology conformance inspection for classes Q and V shall be in accordance with MIL-I-38535 including groups A, B, C, D, and E inspections and as specified herein except where option 2 of MIL-I-38535 permits alternate in-line control testing.
 - 4.4.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 8, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.
- 4.4.2 <u>Group B inspection.</u> The group B inspection end-point electrical parameters shall be as specified in table II herein. For device class S steady-state life tests, the test circuit shall be submitted to the qualifying activity.
- 4.4.3 <u>Group C inspection</u>. The group C inspection end-point electrical parameters shall be as specified in table II herein.
- 4.4.3.1 <u>Additional criteria for device classes M and B</u>. Steady-state life test conditions, method 1005 of MIL-STD-883:
 - a. Test condition C. For device class M, the test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. For device class B, the test circuit shall be submitted to the qualifying activity. For device classes M and B, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005.
 - b. $T_{\Delta} = +125$ °C, minimum.
 - c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
- 4.4.3.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-I-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-I-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-90842
		REVISION LEVEL	SHEET 10

4.4.4 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table II herein.

查询 5962-9084201MGX 供应商 from Finspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein). RHA levels for device classes B, S, Q, and V shall be M, D, R, and H and for device class M shall be M and D. RHA quality conformance inspection sample tests shall be performed at the RHA level specified in the acquisition document.

- a. RHA tests for device classes B and S for levels M, D, R, and H or for device class M for levels M and D shall be performed through each level to determine at what levels the devices meet the RHA requirements. These RHA tests shall be performed for initial qualification and after design or process changes which may affect the RHA performance of the device.
- b. End-point electrical parameters shall be as specified in table II herein.
- c. Prior to total dose irradiation, each selected sample shall be assembled in its qualified package. It shall pass the specified group A electrical parameters in table I for subgroups specified in table II herein.
- PACKAGING
- 5.1 <u>Packaging requirements</u>. The requirements for packaging shall be in accordance with MIL-M-38510 for device classes M, B, and S and MIL-I-38535 for device classes Q and V.
 - NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.1.1 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
 - 6.1.2 <u>Substitutability</u>. Device classes B and Q devices will replace device class M devices.
- 6.2 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using DD Form 1693, Engineering Change Proposal (Short Form).
- 6.3 <u>Record of users</u>. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and which SMD's are applicable to that system. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DESC-EC, telephone (513) 296-6047.
- 6.4 <u>Comments</u>. Comments on this drawing should be directed to DESC-EC, Dayton, Ohio 45444, or telephone (513) 296-5377.
- 6.5 <u>Abbreviations</u>, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-M-38510 and MIL-STD-1331.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-90842
		REVISION LEVEL	SHEET

Military documentation format	Example PIN under new system	Manufacturing source listing	Document <u>listing</u>
New MIL-M-38510 Military Detail Specifications (in the SMD format)	5962-XXXXXZZ(B or S)YY	QPL-38510 (Part 1 or 2)	MIL-BUL-103
New MIL-H-38534 Standardized Military Drawings	5962-XXXXXZZ(H or K)YY	QML-38534	MIL-BUL-103
New MIL-I-38535 Standardized Military Drawings	5962-XXXXXZZ(Q or V)YY	QML-38535	MIL-BUL-103
New 1.2.1 of MIL-STD-883 Standardized Military Drawings	5962-XXXXXZZ(M)YY	MIL-BUL-103	MIL-BUL-103

6.7 Sources of supply.

- 6.7.1 Sources of supply for device classes B and S. Sources of supply for device classes B and S are listed in QFL-38510.
- 6.7.2 <u>Sources of supply for device classes Q and V</u>. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DESC-EC and have agreed to this drawing.
- 6.7.3 <u>Approved sources of supply for device class M</u>. Approved sources of supply for class M are listed in MIL-BUL-103. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-EC.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-90842
		REVISION LEVEL	SHEET 12

DESC FORM 193A JUL 91

037506 _ _ _